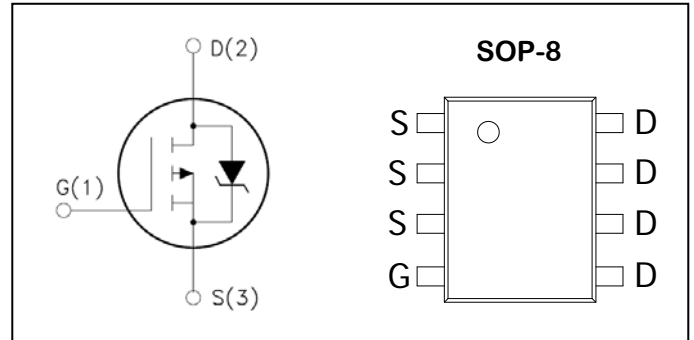


## P-Channel Logic Level Enhancement Mode Field Effect Transistor

### PRODUCT SUMMARY

$V_{DSS}$	$I_D$	$R_{DS(ON)}$ (m $\Omega$ )
-30V	-12A	14m $\Omega$



### Absolute Maximum Ratings ( $T_A = 25^\circ\text{C}$ unless otherwise specified )

Symbol	Parameter	Ratings	Unit
<b>Common Ratings</b>			
$V_{DSS}$	Drain-Source Voltage	-30	V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	
$T_J$	Maximum Junction Temperature	150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$I_S$	Diode Continuous Forward Current	$T_C=25^\circ\text{C}$	A
<b>Mounted on Large Heat Sink</b>			
$I_{DM}$	300 $\mu\text{s}$ Pulse Drain Current Tested(1)	$T_C=25^\circ\text{C}$	A
$I_D$	Continuous Drain Current	$T_C=25^\circ\text{C}$	A
		$T_C=75^\circ\text{C}$	A
$P_D$	Maximum Power Dissipation	$T_C=25^\circ\text{C}$	W
		$T_C=75^\circ\text{C}$	W

### Thermal Characteristics

Symbol	Parameter	Ratings	Unit
$R_{thJC}$	Thermal resistance junction-case max	3	$^\circ\text{C}/\text{W}$
$R_{thJA}$	Thermal resistance junction-ambient max(PCB mounted ) (2)	62.5	$^\circ\text{C}/\text{W}$

1. Pulse width limited by maximum junction temperature.
2. 1-in<sup>2</sup> 2oz Cu PCB board

## Electrical Characteristics (TA=25°C Unless Otherwise Noted)

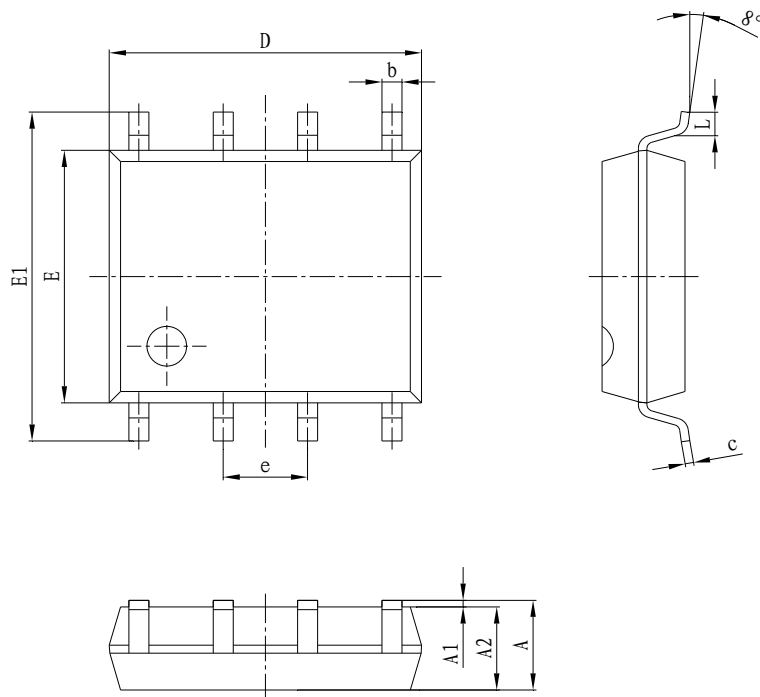
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
<b>On/off Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>DS</sub> =-250uA	-30	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = -30V, V <sub>GS</sub> =0V	--	--	1	uA
		V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V T <sub>J</sub> =125°C	--	--	10	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =-250uA	-1	-1.3	-3	V
I <sub>GSS</sub>	Gate Leakage Current	V <sub>GS</sub> = ± 20V, V <sub>DS</sub> =0V	--	--	± 100	nA
R <sub>DS(ON)</sub>	Drain-Source On-state Resistance(2)	V <sub>GS</sub> = -10V, I <sub>DS</sub> =-12A	--	11	14	mΩ
		V <sub>GS</sub> = -4.5V, I <sub>DS</sub> =-8.5A	--	13	20	
g <sub>FS</sub>	Forward transconductance(2)	V <sub>DS</sub> =- 10V, I <sub>DS</sub> =-7A	--	9	--	S
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> = -8V, Frequency=1.0MHz	--	3204.1	--	pF
C <sub>oss</sub>	Output Capacitance					
C <sub>rss</sub>	Reverse Transfer Capacitance					
<b>Switching Characteristics</b>						
t <sub>d(ON)</sub>	Turn-on Delay Time(1)	V <sub>DS</sub> =-15V, I <sub>D</sub> = -1A, V <sub>GS</sub> = -10V, R <sub>GEN</sub> =15 Ω	--	68.12	--	ns
t <sub>r</sub>	Turn-on Rise Time(1)					
t <sub>d(OFF)</sub>	Turn-off Delay Time(1)					
t <sub>f</sub>	Turn-off Fall Time(1)					
Q <sub>g</sub>	Total Gate Charge(1)	V <sub>DS</sub> =15V, V <sub>GS</sub> = -10V, I <sub>DS</sub> =-11A	--	12.5	--	nC
Q <sub>gs</sub>	Gate-Source Charge(1)					
Q <sub>gd</sub>	Gate-Drain Charge(1)					
<b>Diode Characteristics</b>						
V <sub>SD</sub>	Diode Forward Voltage(2)	I <sub>SD</sub> = -2.1A, V <sub>GS</sub> = 0	--	--	-1.3	V

### NOTES:

- Independent of operating temperature.
- Pulse Test : Pulse width ≤ 300 μ s, Duty cycle ≤ 2%

## PACKAGE MECHANICAL DATA

### SOP-8 Package Dimension



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E1	5.800	6.200	0.228	0.244
E	3.800	4.000	0.150	0.157
e	1.270TYP		0.050TYP	
e1	4.500	4.700	0.177	0.185
L	0.400	1.270	0.016	0.050